



Title of Change:	40V Trench 8 Technology Capacity Expansion by Qualification of ON Semiconductor Aizu, Japan.	
Proposed first ship date:	9 April 2019	
Contact information:	Contact your local ON Semiconductor Sales Office or < Jennie.Shen@onsemi.com >	
Samples:	Contact your local ON Semiconductor Sales Office or < Jennie.Shen@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Robert.Baran@onsemi.com >	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < PCN.Support@onsemi.com >	
Change Part Identification:	New Die part number will be added to wafers with this change	
Change Category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: Aizu Fujitsu Semiconductor Manufacturing, Japan
Description and Purpose:		
<p>This is a Final Change Notification to customers on the qualification of additional wafer fabrication capacity of 60V Trench (T6) MOSFET technology in Aizu Fujitsu Semiconductor Manufacturing (AFSM) located in Aizu, Japan. At the expiration of this notification, all products listed here will be dual sourced from its current ON Semiconductor wafer fab in Gresham and AFSM.</p> <p>There is no product marking change as a result of this change</p>		



Reliability Data Summary:

Qual Vehicle: NTMFS5H400NLT1G

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, _100_% max rated V	1008 hrs	0/231
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/231
HTSL	JESD22-A103	Ta= 175°C	2016 hrs	0/231
IOL	MIL-STD-750	Ta=+25°C, delta Tj=100°C	__30K__ cyc	0/231
	(M1037)	On/off = _2_ min		
	AEC-Q101			
TC	JESD22-A104	Ta= -55_°C to +150_°C	1000_ cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	__192_ hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL __1__ @ __260__ °C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/231
SD	JSTD002	Ta = 245C, 10 sec		0/231

Electrical Characteristic Summary:

Electrical characteristics are not impacted

List of Affected Parts:

Part Number	Qualification Vehicle
NTMFS5H400NLT1G	NTMFS5H400NLT1G
NTMFS5H400NLT3G	
NTMFS5H409NLT1G	
NTMFS5H409NLT3G	
NTMFS5H414NLT1G	